

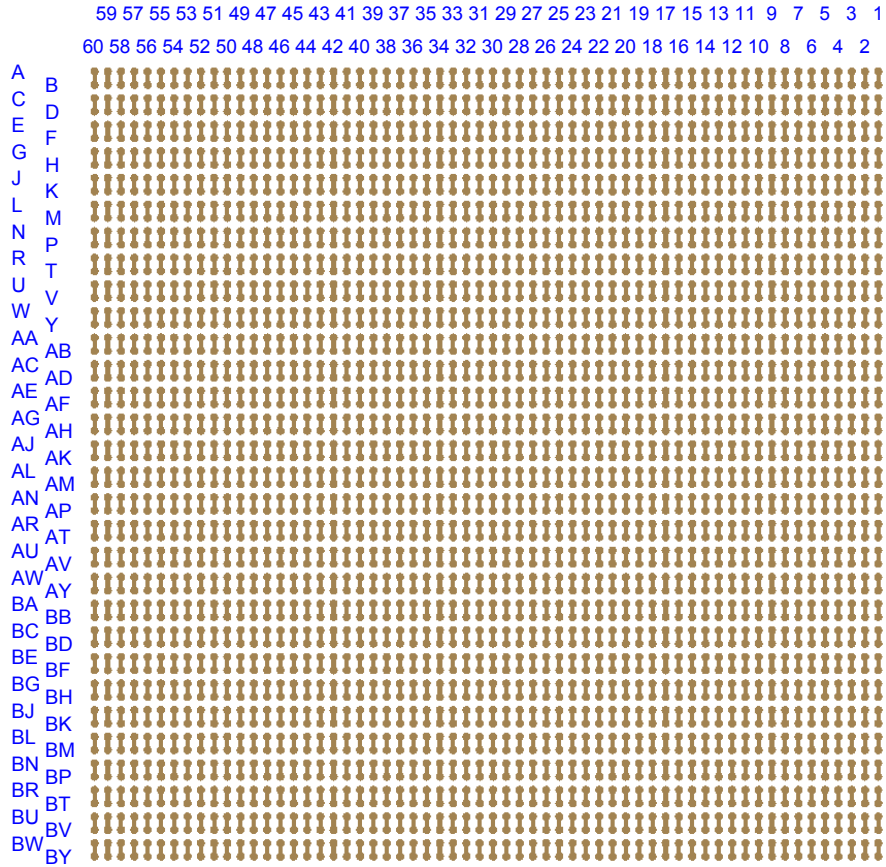
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm (10 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm (8.7 MIL).
- 5) PAD Cu DIAMETER: 0.305mm (12 MIL).
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT or Polyimide).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LPGA3600T.4C-DC609	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LPGA3600T.4C-DC609D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LPGA3600T.4-DC609	Sn63/Pb37	NO	NO	NO
LPGA3600T.4-DC609D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	TopLine®			
DRAWN T.Au	10/30/2013	TITLE LPGA3600T.4-DC609 DAISY CHAIN DUMMY			
ENG M. Hart	10/30/2013				
MFG					
QA		SCALE 3.6:1	SIZE A	DRAWING NO. 546091	REV A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

BALL VIEW



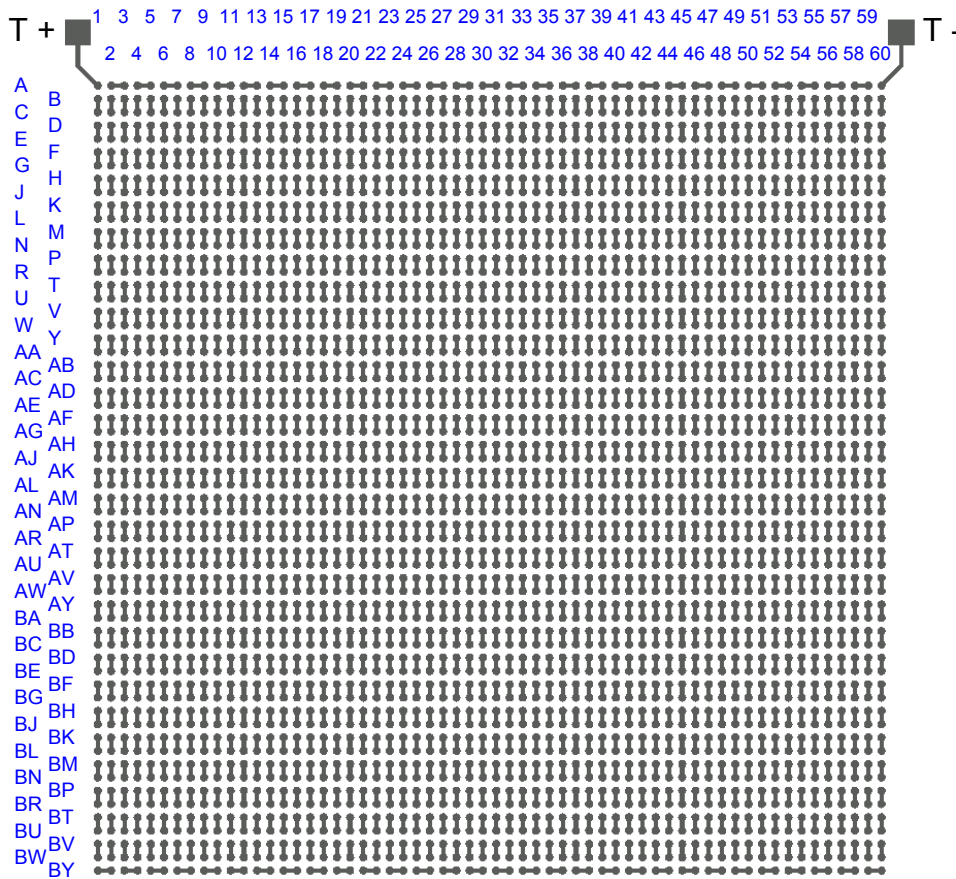
BOTTOM SIDE (TOP X-RAY VIEW)



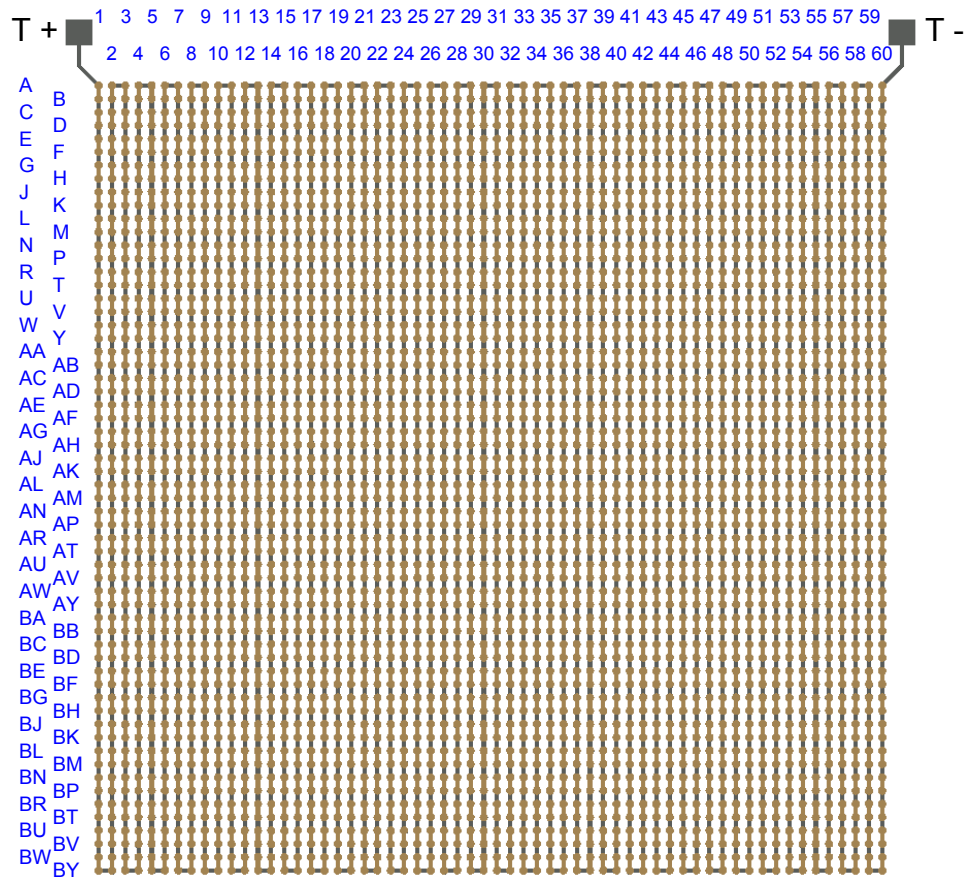
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm (12 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (5 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.22mm (8.7 MIL).

TopLine®			
TITLE		LBGA3600T.4-DC609 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	546091	A
DO NOT SCALE DRAWING			SHEET 2 OF 3



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
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TopLine®			
TITLE		LBGA3600T.4-DC609 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	546091	A
DO NOT SCALE DRAWING			SHEET 3 OF 3